



# Surge Arresters

**Series/Type: EM90XSMD**

The following products presented in this data sheet are being withdrawn.

Ordering Code	Substitute Product	Date of Withdrawal	Deadline Last Orders	Last Shipments
B88069X5241T702		2021-03-19	2021-06-28	2021-09-28

Please contact your nearest TDK sales office if you need support in selecting a suitable substitute. The addresses of our worldwide sales network are presented at [www.tdk-electronics.tdk.com/sales](http://www.tdk-electronics.tdk.com/sales).

**Features**

- Small size
- Fast response time
- High current handling capability
- Stable performance over service life
- Low capacitance and insertion loss
- High insulation resistance
- Excellent SMD handling
- RoHS-compatible

**Applications**

- Power supplies
- Antenna protection
- Air condition
- Modem
- Consumer electronics
- Dataline protection systems

**Electrical specifications**

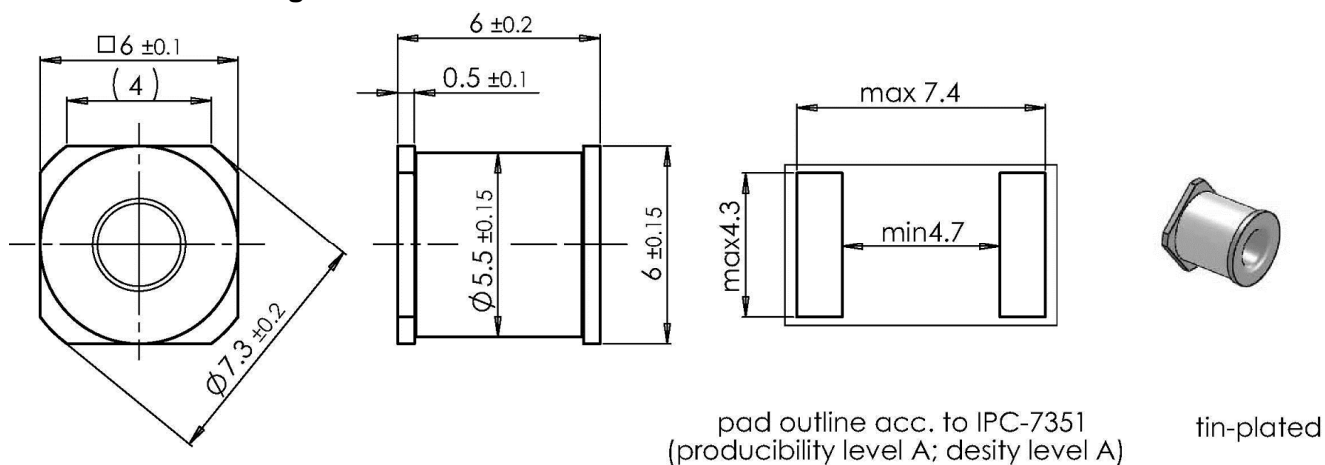
DC spark-over voltage <sup>1) 2)</sup>		90	V
Tolerance		±20	%
Min.		72	V
Max.		108	V
Impulse spark-over voltage			
at 100 V/μs - for 99% of measured values		< 400	V
- typical values of distribution		< 330	V
at 1 kV/μs - for 99% of measured values		< 600	V
- typical values of distribution		< 560	V
Service life			
10 operations	50 Hz, 1 s	2.5	A
1 operation	50 Hz; 0.18 s (9 cycles)	5	A
10 operations [5x (+) & 5x (-)]	8/20 μs	2.5	kA
1 operation	8/20 μs	5	kA
Insulation resistance at 50 V <sub>DC</sub>		> 1	GΩ
Capacitance at 1 MHz		< 1.7	pF
Arc voltage at 1 A		~ 10	V
Glow to arc transition current		< 0.6	A
Glow voltage		~ 60	V
Weight		~ 0.5	g
Operation and storage temperature		-40 ... +125	°C
Climatic category (IEC 60068-1)		40/125/21	
Marking, blue positive		<b>EPCOSEM 90 YY O</b> EM - Series 90 - Nominal voltage YY - Year of production O - Non radioactive	

<sup>1)</sup> At delivery AQL 0.65 level II, DIN ISO 2859

<sup>2)</sup> In ionized mode

Terms in accordance with ITU-T Rec. K.12 and IEC 61643-311.

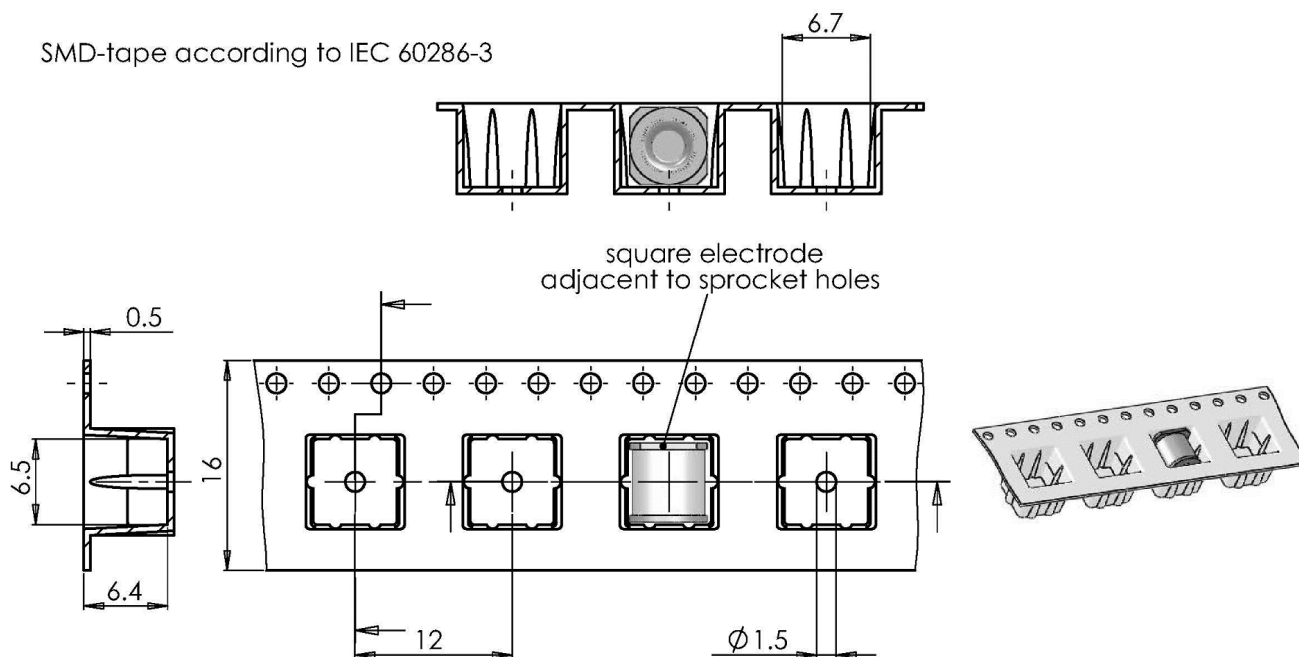
Dimensional drawing in mm



Ordering codes and packing advices

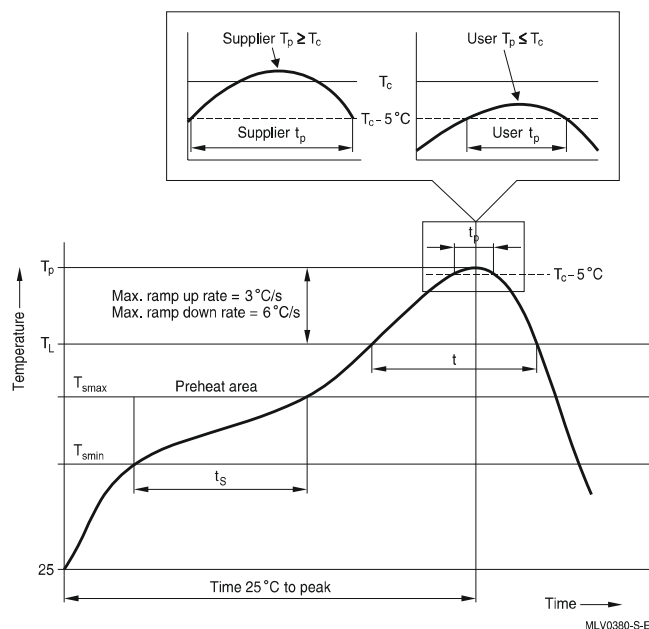
B88069X5241T702 = 700 pcs. on SMD-tape & reel

SMD-tape according to IEC 60286-3



## Soldering parameter

### Reflow soldering



Reflow profile features		Sn- Pb eutectic assembly	Pb-free assembly
Preheat and soak - Temperature min - Temperature max - Time	$T_{smin}$ $T_{smax}$ $t_{smin}$ to $t_{smax}$	100 °C 150 °C 60 ... 120 s	150 °C 200 °C 60 ... 180 s
Average ramp-up rate	$T_{smax}$ to $T_p$	max. 3 °C/ s	max. 3 °C/ s
Liquidous temperature Time at liquidous	$T_L$ $t_L$	183 °C 60 ... 150 s	217 °C 60 ... 150 s
Peak package body temperature *, Classification temperature **	$T_p$ , $T_c$	220 ... 235 °C **	245 ... 260 °C **
Time ( $t_p$ ) ** within 5 °C of the specified classification temperature ( $T_c$ )		20 s ***	30 s ***
Average ramp-down rate	$T_p$ to $T_{smax}$	max. 6 °C/ s	max. 6 °C/ s
Time 25 °C to peak temperature		max. 6 min	max. 8 min

\* = Tolerance for peak profile temperature ( $T_p$ ) is defined as a supplier minimum and a user maximum.  
 \*\* = For details please refer to JEDEC J-STD-020D.  
 \*\*\* = Tolerance for time at peak profile temperature ( $t_p$ ) is defined as a supplier minimum and a user maximum.

Surface mounted components (SMD) may exhibit a temporary increase in the DC spark-over voltage after the solder reflow process. The components will recover within 24 hours. There is no quality defect nor change in protection levels during the temporary change in DC spark-over voltage.

### Cautions and warnings

- Do not operate surge arresters in power supply networks, whose maximum operating voltage exceeds the minimum spark-over voltage of the surge arresters.
- Surge arresters may become hot in the event of longer periods of current stress (burn risk). In the event of overload the connectors may fail or the component may be destroyed.
- Surge arresters must be handled with care and must not be dropped.
- Do not continue to use damaged surge arresters.
- The shown SMD pad dimensions represent a safe way to mount the arrester and are a recommendation of the manufacturer. During the reflow process it must be assured that no solder material reduces the insulation distance between the pads below the arrester.
- SMD surge arresters should be soldered within 24 month after shipment.

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3. **The warnings, cautions and product-specific notes must be observed.**
4. In order to satisfy certain technical requirements, **some of the products described in this publication may contain substances subject to restrictions in certain jurisdictions (e.g. because they are classed as hazardous)**. Useful information on this will be found in our Material Data Sheets on the Internet ([www.tdk-electronics.tdk.com/material](http://www.tdk-electronics.tdk.com/material)). Should you have any more detailed questions, please contact our sales offices.
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## Important notes

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